

IN THE CLAIMS

Please cancel claims 1-11 and 14-20 without prejudice or disclaimer to the subject matter therein. Please amend claims 12 and 13 as follows.

12. (Amended) A semiconductor arrangement comprising a bump electrode having a first protrusion and a second protrusion bonded to an IC electrode on a circuit forming surface of a semiconductor element,

wherein said first and second protrusions are in contact with or close to an electrode on a circuit board when the semiconductor element is mounted on the circuit board,

wherein said first protrusion has a formed portion formed by forming a melted portion of a wire with a capillary and solidifying the melted portion, and a wire material portion comprising a portion of the wire in a vicinity of the melted portion, said wire material portion extending from a vertex portion of said formed portion downward from said vertex portion and being bonded to said formed portion, and

wherein said wire material portion does not contact the IC electrode or the circuit forming surface.

13. (Amended) A semiconductor arrangement as claimed in claim 12, wherein the electrode on the circuit board and said bump electrode are electrically connected to each other.

Please add new claims 21-24 as follows.

21. (New) A semiconductor arrangement as claimed in claim 12, wherein said first and second protrusions have an amount of conductive adhesive by which the IC electrode of the semiconductor element can be connected to said bump electrode.

22. (New) A semiconductor arrangement as claimed in claim 12, wherein said vertex portion of said first protrusion has a flat surface portion and a vertex portion of said second protrusion has a flat surface portion.

23. (New) A semiconductor arrangement as claimed in claim 22, wherein said flat surface portion of said first protrusion and said flat surface portion of said second protrusion have substantially a same height.

24. (New) A semiconductor arrangement as claimed in claim 12, wherein said second protrusion is formed from a portion of the wire extending upward from said wire material portion bonded to said formed portion.